

# **FORESEE DDR4 SO-DIMM 2666 Datasheet**

**Version: 1.0**



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**Revision History**

Revision No.	History	Draft Date	Remark
1.0	Release	Dec 2019	

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## 1. Type

ECC DDR4 SO-DIMM 260PIN

## 2. Full conception

DDR4 SDRAM Unbuffered DIMM, It supports 1.2V low voltage mode. Design 260PIN golden finger interface protocols, and it supports two dual channel applications.

## 3. Design refer

JEDEC ECC DDR4 R/C

## 4. Product Name

Industrial Memory

## 5. Capacity information

DDR4 8GB/16GB

## 6. Book Sheet

Type	Capacity	Speed	HV P/N
ECC SO-DIMM	8 GB	2666	FD4AX2666C8GSC
ECC SO-DIMM	16 GB	2666	FD4AX2666CQGSC

## 7. Specification

Specification	JEDEC ECC DDR4 Reference
Interface	DDR4 260PIN SO-DIMM
Capacity	8/16/GB
Speed	2666Mbps
CAS Latency	19
Organization	1/2 Rank x8
Voltage	1.2V
Operating Temp.	0~85°C (Surface)
Storage Temp.	-40°C ~ +85°C
Form Factor	69.6 * 30 mm
Application	Industrial (general reference)

## 8. PCB Specifications

### General

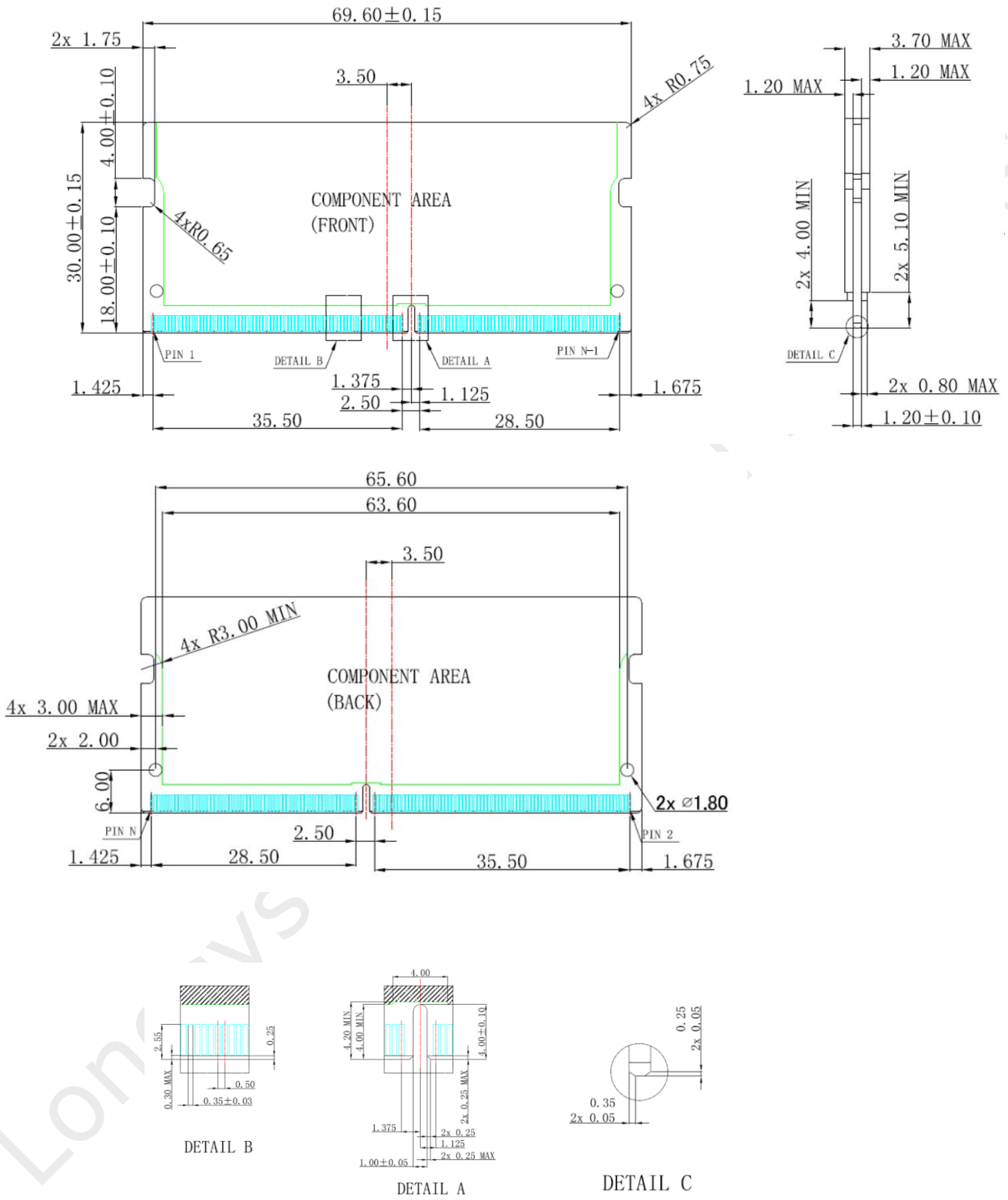
1. Board size: 69.6 x 30 mm ± 0.15 mm
2. Thickness: 1.2 ± 0.1 mm
3. Pin count: 260 PIN

### PCB Material

1. RoHS
2. Glass Epoxy FR4, .UL 94V-0

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**9. Module Dimensions**



Units: millimeters

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